Materials Declaration

Package	LQFP
Body Size	7 X 7
LeadCount	48
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	86	5.32 E-02	385996
Epoxy resin	8	4.94 E-03	35907
Phenol Resin	5	3.09 E-03	22442
Sb2O3	0.4	2.47 E-04	1795
Brominated Resin	0.4	2.47 E-04	1795
Carbon Black	0.2	1.24 E-04	898
Subtotal		6.18 E-02	448833

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	4.93 E-02	358195
Ni	3	1.54 E-03	11170
Si	0.65	3.33 E-04	2420
Mg	0.15	7.69 E-05	559
Subtotal		5.13 E-02	372344

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	8.00 E-04	5810

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	2.50 E-03	18155

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	9.74 E-04	7070

Chip

	% of Chip	Weight (g)	PPM
Si	100	1.85 E-02	134465

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	74	1.36 E-03	9859
Resin	26	4.77 E-04	3464
Subtotal		1.83 E-03	13323

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A /3052. ICP-OES
Cd	Not Detected	EPA Method 3051A /3052. ICP-OES
Hg	Not Detected	EPA Method 3051A /3052. ICP-OES
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A /3052. ICP-OES
Cd	Not Detected	EPA Method 3051A /3052. ICP-OES
Hg	Not Detected	EPA Method 3051A /3052. ICP-OES
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS

Package Totals

Weight (g)	PPM
1.38 E-01	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ADI Proprietary

Materials Declaration

Package	LQFP
Body Size	7 X 7
LeadCount	48
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	86	5.32 E-02	385996
Epoxy resin	8	4.94 E-03	35907
Phenol Resin	5	3.09 E-03	22442
Sb2O3	0.4	2.47 E-04	1795
Brominated Resin	0.4	2.47 E-04	1795
Carbon Black	0.2	1.24 E-04	898
Subtotal		6.18 E-02	448833

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	4.93 E-02	358195
Ni	3	1.54 E-03	11170
Si	0.65	3.33 E-04	2420
Mg	0.15	7.69 E-05	559
Subtotal		5.13 E-02	372344

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	8.00 E-04	5810

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	2.13 E-03	15431
Pb	15	3.75 E-04	2723
Subtotal		2.50 E-03	18155

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	9.74 E-04	7070

Chip

	% of Chip	Weight (g)	PPM
Si	100	1.85 E-02	134465

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	74	1.36 E-03	9859
Resin	26	4.77 E-04	3464
Subtotal		1.83 E-03	13323

Molding Compound

Item	PPM	Method
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Cd	Not Detected	EPA Method 3051A /3052. ICP-OES
Hg	Not Detected	EPA Method 3051A /3052. ICP-OES
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PBB	Not Detected	EPA Method 3540C/3550C. GC/MS
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS

Die Attach Paste

Item	PPM	Method
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Package Totals

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